

**AMENDMENTS TO THE CLAIMS**

This listing of claims replaces all prior versions of claims in the application.

1-12. (Cancelled)

13. (Currently Amended): A semiconductor device comprising a plurality of alignment marks formed over a semiconductor wafer,

each of the alignment marks being divided by a micronized line-and-space pattern into a plurality of lines extending along a first direction,

each of the plural lines being divided ~~[[into]]~~ in a broken line having a plurality of segments which are arranged in the first direction only, ~~and wherein all of the alignment marks formed in the entire alignment mark area have the same shape so as to generate about the same field image alignment signal, and positions of the divisions between~~ the plurality of segments of the lines ~~[[are]]~~ being positioned offset in the first direction from those of the divisions between the plurality of segments of their adjacent lines,

wherein all of the alignment marks formed in an entire alignment mark area have a same shape so as to generate about a same field image alignment signal.

14. (Cancelled).

Application No.: 10/073,314  
Art Unit: 2894

Amendment under 37 C.F.R. §1.111  
Attorney Docket No.: 020171

15. (Previously Presented): A semiconductor device according to claim 13, wherein  
a margin in which the micronized pattern is formed is larger than a margin for a  
memory cell pattern to be formed on the semiconductor wafer.

16-17. (Cancelled)